



Product Change Notification: NTD0-11USUI436

Date:

12-Feb-2025

Product Category:

32-Bit Microcontrollers

Notification Subject:

CCB 7412 Initial Notice: Qualification of palladium-coated copper with gold flash (CuPdAu) as a new wire material for ATSAM4LS2CA, ATSAM4LC8CA, ATSAM4LS8CA, AT32UC3A1512, AT32UC3A1128, AT32UC3A1256, ATSAM4LC4CA, ATSAM4LS4CA, ATSAM4LC2CA, AT32UC3C1128C, AT32UC3C1256C, AT32UC3C1512C and AT32UC3C164C device families available in 100L TQFP (14x14x1mm) package assembled at MMT assembly site.

Affected CPNs:

[NTD0-11USUI436_Affected_CPN_02122025.pdf](#)

[NTD0-11USUI436_Affected_CPN_02122025.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium-coated copper with gold flash (CuPdAu) as a new wire material for ATSAM4LS2CA, ATSAM4LC8CA, ATSAM4LS8CA, AT32UC3A1512, AT32UC3A1128, AT32UC3A1256, ATSAM4LC4CA, ATSAM4LS4CA, ATSAM4LC2CA, AT32UC3C1128C, AT32UC3C1256C, AT32UC3C1512C and AT32UC3C164C device families available in 100L TQFP (14x14x1mm) package assembled at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change

Assembly Site	Microchip Technology Thailand (MMT)	Microchip Technology Thailand (MMT)
Wire Material	Au	CuPdAu
Die Attach Material	3280	3280
Molding Compound Material	G700HA	G700HA
Lead-Frame Material	C7025	C7025
Lead-Frame Design	See pre and post change summary for comparison	

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as a new wire material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: March 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	February 2025					March 2025				
Work Week	05	06	07	08	09	10	11	12	13	14
Initial PCN Issue Date			X							

Qual Report Availability									X	
Final PCN Issue Date									X	

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 12, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_NTDO-11USUI436_Qual_Plan.pdf

PCN_NTDO-11USUI436_Pre and Post_Change_Summary.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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